

Product Change Notification - KSRA-30CVPA719

Date:

11 Apr 2018

Product Category:

Capacitive Touch Sensors; 8-bit PIC Microcontrollers

Affected CPNs:

Notification subject:

CCB 3210 Initial Notice: Qualification of MTAI as a new assembly site for selected Atmel Products available in 32L VQFN package using gold (Au) bond wire

Notification text:

PCN Status:

Initial notification

PCN Type:

Manufacturing Change

Microchip Parts Affected:

Please open one of the icons found in the Affected CPNs section above.

NOTE: For your convenience Microchip includes identical files in two formats (.pdf and .xls).

Description of Change:

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Pre Change:

Assembled at ANAC Assembly site with punched singulation method using 8290 die attach and 146x146 mils lead frame paddle size

Post Change:

Assembled at MTAI Assembly site with sawn singulation method using 3280 die attach and 150x150 mils paddle size.

Pre and Post Change Summary:

	Pre Change	Post Change			
Assembly Site	Amkor Assembly & Test (Shanghai) Co., LTD / ANAC	Microchip Technology Thailand (HQ) / MTAI			
Wire material	Au	Au			
Die attach material	8290	3280			
Molding compound material	G700	G700			
Lead frame material	C194	C194			
Paddle Size	146x146 mils	150x150 mils			
Singulation Method	Punched	Sawn			

Impacts to Data Sheet:

None

Change Impact:

None

Reason for Change:



To improve manufacturability by qualifying MTAI as a new assembly site

Change Implementation Status:

In Progress

Estimated Qualification Completion Date:

May 2018

Note: Please be advised the qualification completion times may be extended because of unforeseen business conditions however implementation will not occur until after qualification has completed and a final PCN has been issued. The final PCN will include the qualification report and estimated first ship date. Also note that after the estimated first ship date guided in the final PCN customers may receive pre and post change parts.

Time Table Summary:

		March 2018					May 2018				
Workweek	09	10	11	12	13		18	19	20	21	22
Initial PCN Issue Date		Χ									
Qual Report Availability											Χ
Final PCN Issue Date											Χ

Method to Identify Change:

Traceability code

Qualification Plan:

Please open the attachments included with this PCN labeled as PCN_#_Qual_Plan.

Revision History:

March 05, 2018: Issued initial notification.

April 11, 2018: Re-issued initial notification to include singulation method and revise post change data.

The change described in this PCN does not alter Microchip's current regulatory compliance regarding the material content of the applicable products.

Attachment(s):

PCN_KSRA-30CVPA719_Qual_Plan.pdf

Please contact your local Microchip sales office with questions or concerns regarding this notification.

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Affected Catalog Part Numbers (CPN)

AT42QT4160-MUR

ATMEGA168-20MQ

ATMEGA168-20MQR

ATMEGA168-20MU

ATMEGA168-20MUR

ATMEGA168P-20MQ

ATMEGA168P-20MQR

ATMEGA168P-20MU

ATMEGA168P-20MUR

ATMEGA168PV-10MU

ATMEGA168PV-10MUR

ATMEGA168PV-10MUR455

ATMEGA168V-10MQ

ATMEGA168V-10MQR

ATMEGA168V-10MQR610

ATMEGA168V-10MU

ATMEGA168V-10MUR

ATMEGA168V-10MUR598

ATMEGA328-MU

ATMEGA328-MUR

ATMEGA328P-MN

ATMEGA328P-MNR

ATMEGA328P-MU

ATMEGA328P-MUR

Date: Tuesday, April 10, 2018